

104071-2 ✓ ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 104071-2

PCB Mount Header, Vertical, Board-to-Board, 5 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **5**

Number of Rows: **1**

## Features

### Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	5
Number of Rows	1
Board-to-Board Configuration	Parallel

### Electrical Characteristics

Dielectric Withstanding Voltage (Max)	500 VAC
Insulation Resistance	5000 MΩ
Operating Voltage	30 VAC

### Body Features

Connector Profile	Standard
Primary Product Color	Black



### Contact Features

Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 $\mu\text{m}$ [150 – 250 $\mu\text{in}$ ]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular Post
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 $\mu\text{m}$ [30 $\mu\text{in}$ ]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

### Termination Features

Round Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

### Mechanical Attachment

Mating Retention	With
Mating Retention Type	Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

### Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP

### Dimensions

PCB Thickness (Recommended)	1.57 mm[.062 in]
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### Usage Conditions

Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 $^{\circ}\text{C}$ [-85 – 221 $^{\circ}\text{F}$ ]



### Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

### Industry Standards

UL Rating	Recognized
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0

### Packaging Features

Packaging Quantity	42
Packaging Type	Box, Tube

### Other

Position Locations Omitted	0
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) SVHC > Threshold: Pb (13% in Component Part) <b>Article Safe Usage Statements:</b> Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part

numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Also in the Series | AMPMODU System 50



## Documents

### Product Drawings

05 SYSTEM 50 HDR SRST SHRD

English

### CAD Files

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_104071-2\\_T.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_104071-2\\_T.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_104071-2\\_T.3d\\_stp.zip](#)

English

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**Product Specifications**

[Application Specification](#)

English

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**Product Environmental Compliance**

[TE Material Declaration](#)

English